

What is claimed is:

5 1. An article of manufacture for the prevention of the increase of temperature in heat sensitive devices through the absorption of heat during heat generating conditions comprising

10 an amount of boric acid sufficient to effect the required heat absorption; and

15 means for supporting said boric acid, the physical characteristics of said means for supporting said boric acid being defined by the heat absorbing application.

20 2. The article of manufacture according to Claim 1, wherein the means for supporting said boric acid further comprises a retaining matrix, packaging, encapsulation, microencapsulation, enclosure or structure to form a heat absorbing surface, device or structure.

25 3. The article of manufacture according to claim 1, wherein the heat sensitive device is embedded within the boric acid.

30 4. The article of manufacture according to claim 1, wherein the heat sensitive device is surrounded by the boric acid.

5. The article of manufacture according to claim 1, wherein the means for supporting said boric acid is a closed container, in which said boric acid is located.

6. The article of manufacture according to claim 5, wherein said boric acid lines the inner wall of the closed container.

7. The article of manufacture according to claim 6, wherein said heat sensitive device is located within and spaced from said boric acid.

5 8. The article of manufacture according to claim 1, wherein said boric acid is adhered to a flexible substrate, said substrate being adaptable to the size and shape of said heat sensitive device.

10 9. The article of manufacture according to claim 1, wherein the means for supporting said boric acid is the boric acid itself.

15 10. A method for preventing the increase of temperature in heat sensitive devices through the absorption of heat during heat generating conditions comprising the steps of:

(a) providing an amount of boric acid sufficient to effect the required heat absorption;

20 (b) supporting said boric acid in a position between the heat sensitive device and ^athe heat generator;

25 so as to absorb the heat and prevent any increase in the temperature of the heat sensitive device.

30 11. The method as recited in claim 9, wherein said boric acid is provided in accordance with any one of claims 1 through 8.

35 12. A method for preventing the increase of temperature in a heat sensitive device through the absorption of the heat sensitive device's self-generated heat, during heat generating conditions, comprising the steps of:

(a) providing an amount of boric acid sufficient to effect the required heat absorption;

(b) contacting said boric acid to the heat sensitive device;

so as to absorb the heat sensitive device's self generating heat and prevent any increase in its temperature.

10 13. The method as recited in claim 11 wherein said boric acid is provided in accordance with any one of claims 1 through 8.

15 3 14. A method for preventing the increase of temperature in a heat sensitive device through the absorption of the heat sensitive device's self-generated heat, during heat generating conditions, comprising the steps of:

20 (a) providing an amount of boric acid sufficient to effect the required heat absorption;

(b) indirectly contacting said boric acid to the heat sensitive device;

25 so as to absorb the heat sensitive device's self generating heat and prevent any increase in its temperature.

30 15. The method as recited in claim 13 wherein said boric acid is provided in accordance with any one of claims 1 through 8.

16. The use of boric acid in an amount sufficient to absorb a predetermined amount of heat as a heat absorbing device for the protection of heat sensitive devices and life.

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